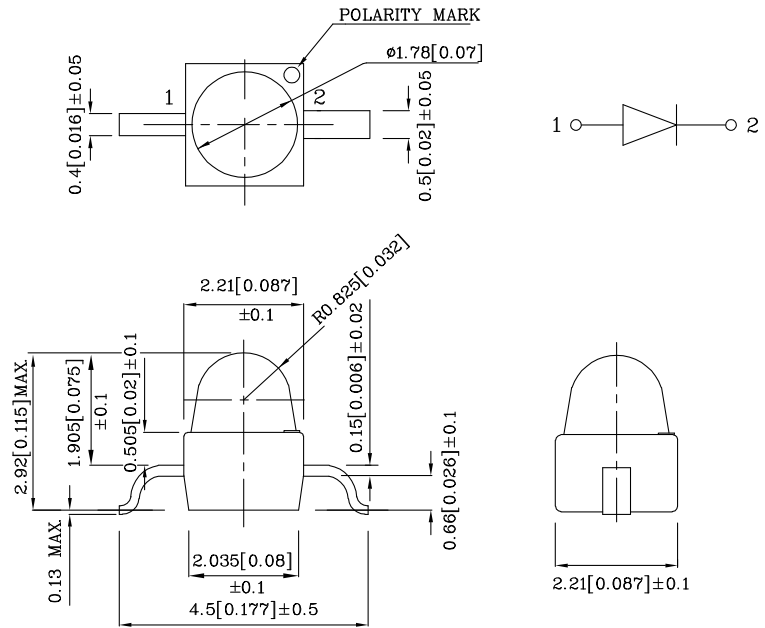


PRELIMINARY SPEC

Features

- SUBMINIATURE PACKAGE.
- GULL WING.
- LONG LIFE - SOLID STATE RELIABILITY.
- LOW PACKAGE PROFILE.
- PACKAGE :1000PCS / REEL.
- RoHS COMPLIANT.



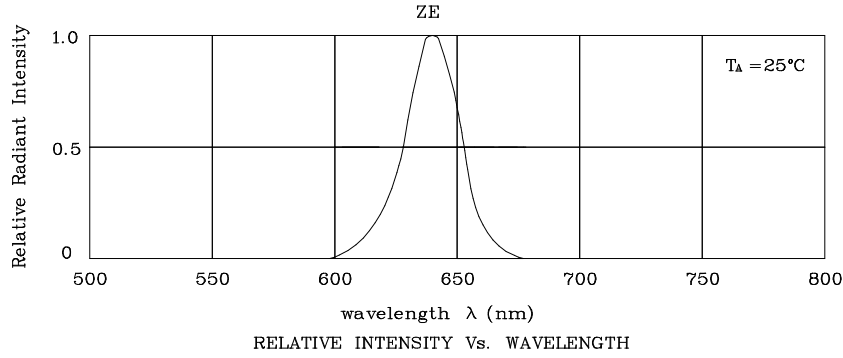
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25(0.01") unless otherwise noted.

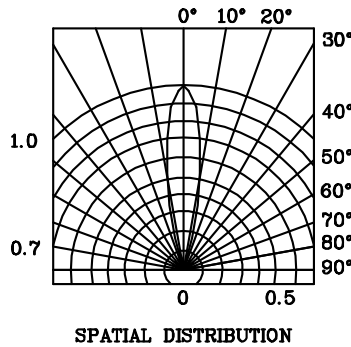
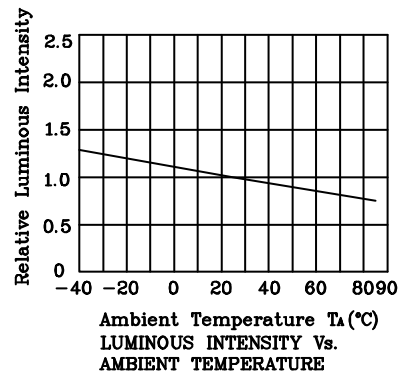
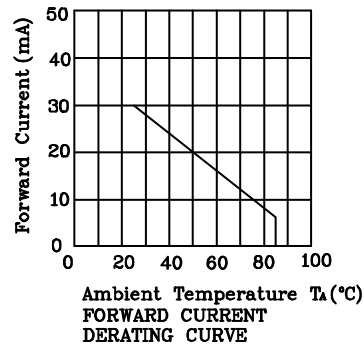
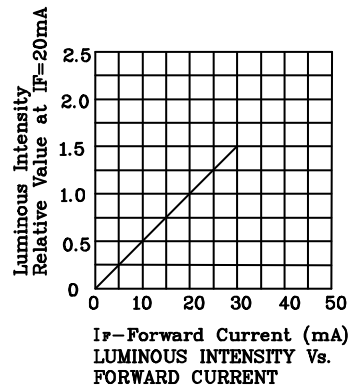
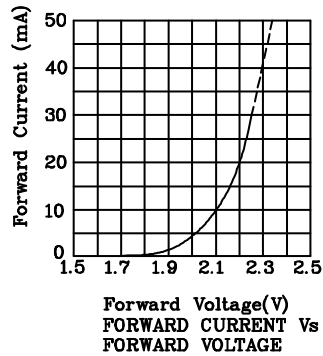
Absolute maximum ratings (TA=25°C)		ZE (InGaAlP)	Unit
Reverse voltage	VR	5	V
Forward current	IF	30	mA
Forward current (peak) 1/10Duty cycle 0.1ms pulse width	iFS	150	mA
Power dissipation	PT	120	mW
Operating temperature	TA	-40 ~ +85	°C
Storage temperature	Tstg	-40 ~ +85	

Operating Characteristics (TA=25°C)		ZE (InGaAlP)	Unit
Forward voltage (typ.) (IF=20mA)	VF	2.2	V
Forward voltage (max.) (IF=20mA)	VF	2.8	V
Reverse current (VR=5V)	IR	10	uA
Wavelength at peak emission (IF=20mA)	λ peak	640	nm
Wavelength of dominant emission (IF=20mA)	λ D	630	nm
Spectral Line half-width (IF=20mA)	Δλ	25	nm
Capacitance (VF=0V, f=1MHz)	C	27	pF

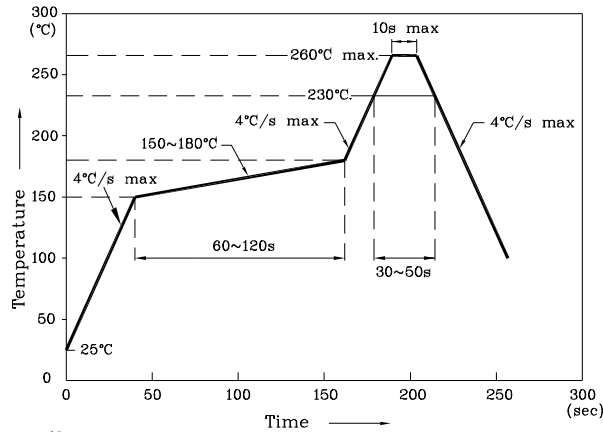
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Wavelength nm λ P	Viewing Angle 2θ 1/2
				min.	typ.		
XZZE64W-3	Red	InGaAlP	Water Clear	1500	2490	640	20°



❖ ZE



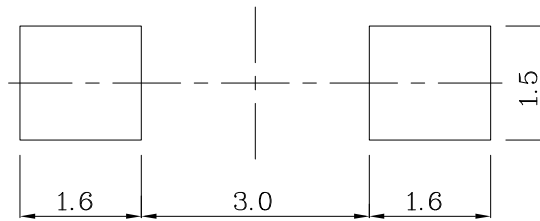
Reflow Soldering Profile For Lead-free SMT Process.



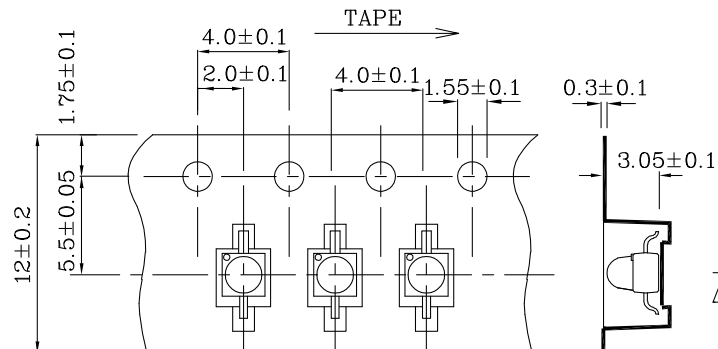
Notes:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C~260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units: mm ; Tolerance: ± 0.1)



❖ Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.